

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHIEN-FA LEE	08/16/2016
HSU-SHUI LIU	08/22/2016
JIUN-RONG PAI	08/16/2016
PIN-YI HSIN	08/25/2016
SHOU-WEN KUO	08/25/2016
PATRICK LIN	08/24/2016
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<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16853846
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<b>ATTORNEY DOCKET NUMBER:</b>	TSMCP747USA
<b>NAME OF SUBMITTER:</b>	JAMES R. POTASHNIK
<b>SIGNATURE:</b>	/James R. Potashnik/
<b>DATE SIGNED:</b>	04/21/2020

PATENT

**Total Attachments: 8**

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**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):  
Chien-Fa Lee

Assignor(s):  
Hsu-Shui Liu

Assignor(s):  
Jiun-Rong Pai

Assignor(s):  
Pin-Yi Hsin

Assignor(s):  
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Assignor(s):  
Patrick Lin

Assignee:  
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Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
"INTEGRATED CHIP DIE CARRIER EXCHANGER" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this  
Assignment on the same day as he/she signs the Declaration); or

was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

I hereby authorize and request my attorney associated with Customer No.  
107476, to insert on the designated lines below the filing date and application  
number of said application when known:

U.S. Serial No. \_\_\_\_\_  
filed on \_\_\_\_\_

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/16/06  
Date

Chien Fa Lee  
Name 1<sup>st</sup> Inventor Chien-Fa Lee

TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/22/2016  
Date

Hsu-Shui Liu  
Name 2<sup>nd</sup> Inventor Hsu-Shui Liu

TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/16/2016  
Date

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TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/15/2016

Date

Pin-Yi Hsin

Name 4<sup>th</sup> Inventor Pin-Yi Hsin

TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/17 2016  
Date

Shou Wen Kuo  
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TSMC Docket No. P20160369US00  
Docket No. TSMCP747US

8/24 2016  
Date

Patrick Lin  
Name 6<sup>th</sup> Inventor Patrick Lin